



VMDSEMI

VFTL010R077NA

Datasheet



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General Description

Symbol

$V_{(BR)DSS}$	$R_{DS(ON)_{max}}$	I_D
100V	7.7mΩ@10V	80A

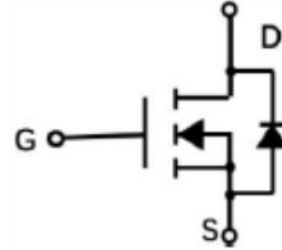
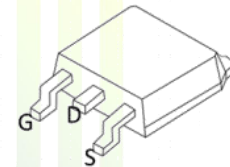


Figure 1 Symbol of VFTL010R077NA

Features

- Split Gate Trench Technology
- Low $R_{DS(ON)}$
- Low Gate Charge
- Low Gate Resistance
- 100% UIS Tested

Package Type



TO-252-2L

Application

- Industrial Power Supply
- Load Switch

Figure 2 Package Type of VFTL010R077NA

Ordering Information

Product Name	Package
VFTL010R077NA	TO-252-2L

Absolute Maximum Ratings ($T_A = 25\text{ }^\circ\text{C}$, unless otherwise specified)

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V_{DSS}	100	V
Gate-Source Voltage	V_{GSS}	± 20	V
Continuous Drain Current ^{Note1}	I_D	80	A
Pulsed Drain Current ^{Note2}	I_{DM}	320	
Avalanche Current ^{Note3}	I_{AS}	39	
Single Pulsed Avalanche Energy ^{Note3}	E_{AS}	380	mJ
Total Power Dissipation ^{Note5}	P_D	89	W
Junction Temperature	T_J	150	$^\circ\text{C}$
Storage Temperature	T_{STG}	-55 to 150	$^\circ\text{C}$

Thermal Resistance

Parameter	Symbol	Min	Typ	Max	Unit
Thermal Resistance, Junction-to-Ambient ^{Note6}	$R_{\theta JA}$		50		$^\circ\text{C/W}$
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$		1.4		$^\circ\text{C/W}$



Electrical Characteristics ($T_J = 25^\circ\text{C}$, unless otherwise specified)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Statistic Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0V, I_D=250\mu A$	100			V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=80V, V_{GS}=0V$			1	μA
Gate-Body Leakage Current	I_{GSS}	$V_{GS} = \pm 20V, V_{DS}=0V$			± 100	nA
Gate Threshold Voltage ^{Note4}	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	1	2	3	V
Static Drain-Source On-Resistance ^{Note4}	$R_{DS(ON)}$	$V_{GS}=10V, I_D=20A$		6.7	7.7	mΩ
Forward Transconductance ^{Note4}	g_{FS}	$V_{DS}=10V, I_D=10A$		29		S
Dynamic Characteristics						
Input Capacitance	C_{ISS}	$V_{DS}=50V$		2915		pF
Output Capacitance	C_{OSS}	$V_{GS}=0V$		370		pF
Reverse Transfer Capacitance	C_{RSS}	$f=1MHz$		16		pF
Total Gate Charge	Q_g	$V_{DS}=50V$		55		nC
Gate-Source Charge	Q_{gs}	$V_{GS}=10V$		18		
Gate-Drain Charge	Q_{gd}	$I_D=45A$		14		
Gate Resistance	R_g	$f=1MHz, \text{Open drain}$		1.2		Ω
Switching Parameters						
Turn-on Delay Time	$t_{d(on)}$	$V_{DD}=50V$		15		ns
Turn-on Rise Time	t_r	$V_{GS}=10V$		10		
Turn-off Delay Time	$t_{d(off)}$	$R_L=1.2\Omega$		32		
Turn-off Fall Time	t_f	$R_G=3\Omega$		10		
Diode Characteristics						
Diode Forward Voltage ^{Note4}	V_{SD}	$V_{GS}=0V, I_S=10A$			1.2	V

Notes :

- The maximum current rating is limited by package. And device mounted on a large heatsink.
- Pulse Test : Pulse Width $\leq 10\mu s$, duty cycle $\leq 1\%$.
- E_{AS} condition: $V_{DD} = 50V, V_{GS} = 10V, L = 0.5mH, R_G=25\Omega$ Starting $T_J = 25^\circ\text{C}$.
- Pulse Test : Pulse Width $\leq 300\mu s$, duty cycle $\leq 2\%$.
- The power dissipation P_D is limited by $T_{J(MAX)} = 150^\circ\text{C}$. And device mounted on a large heatsink
- Device mounted on $1in^2$ FR-4 board with 2oz. Copper, in a still air environment with $T_A = 25^\circ\text{C}$.

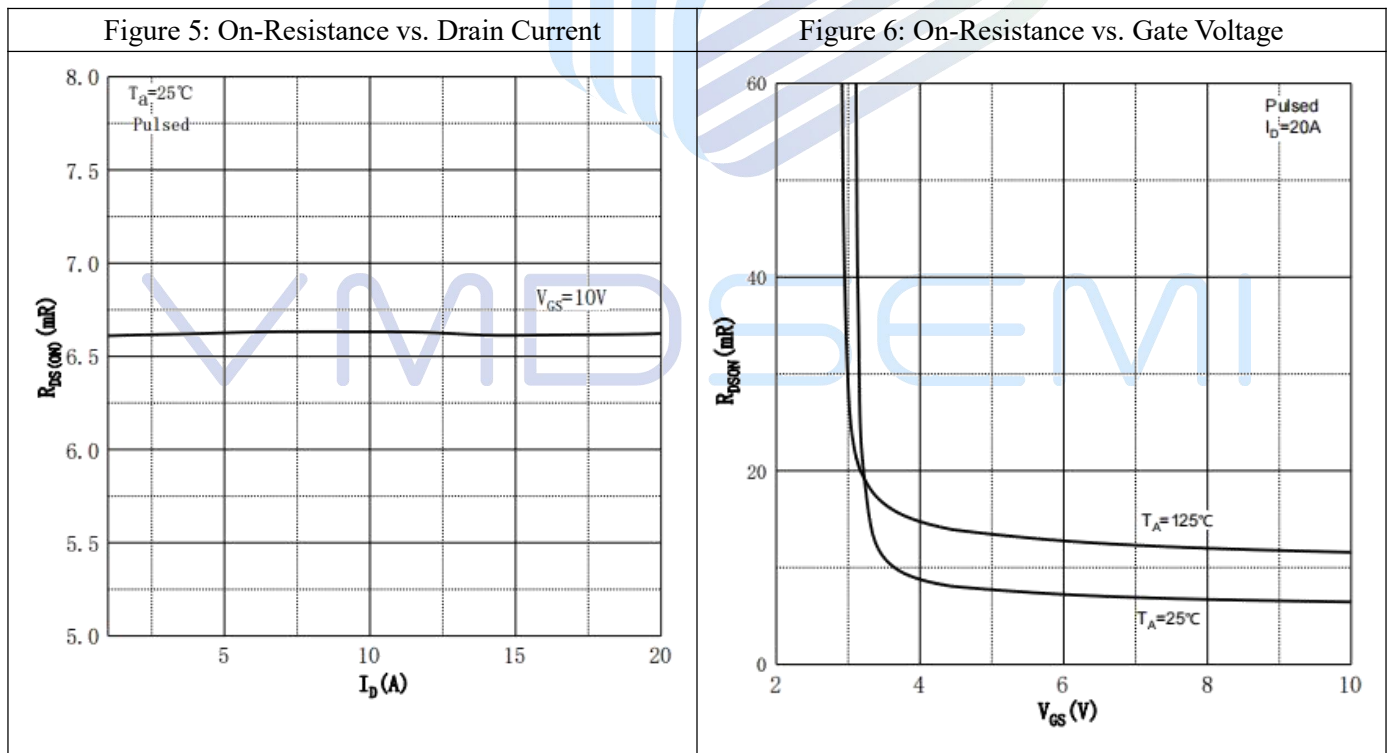
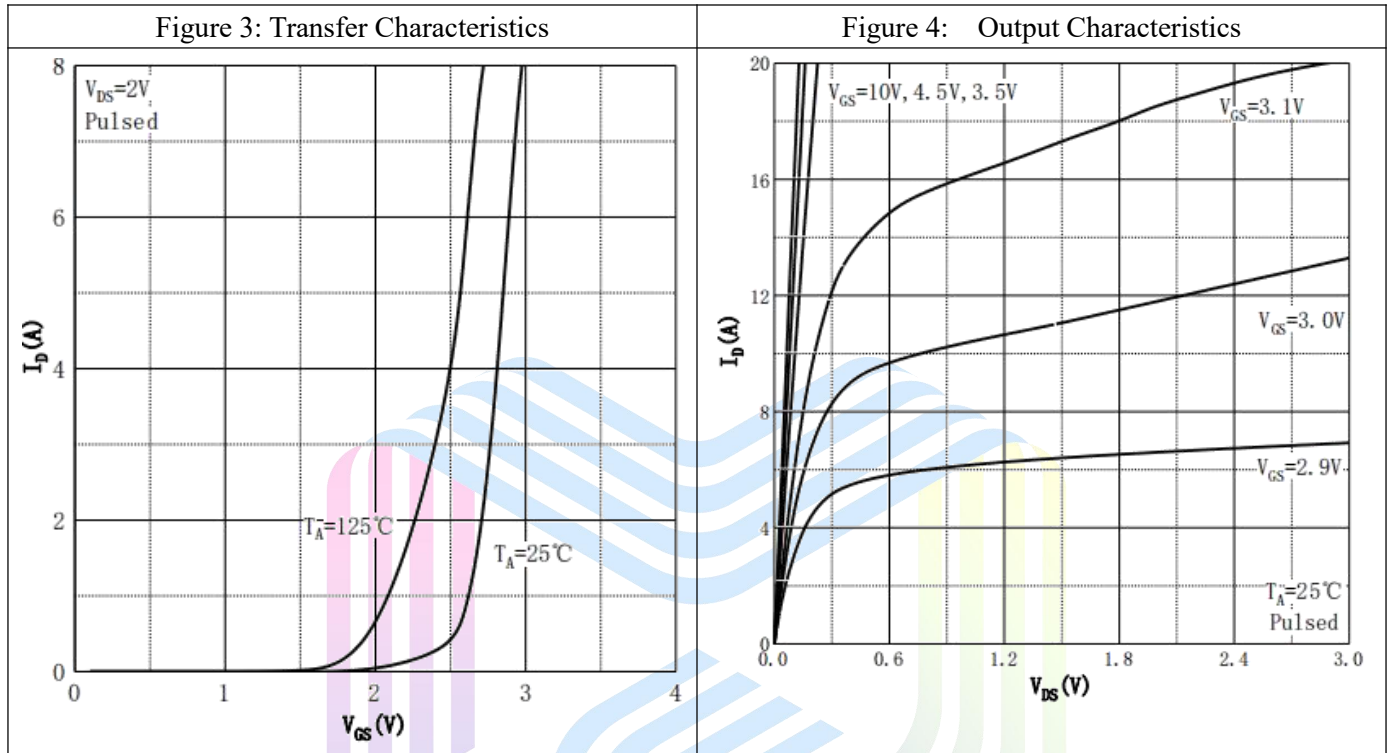
Typical Performance Characteristics


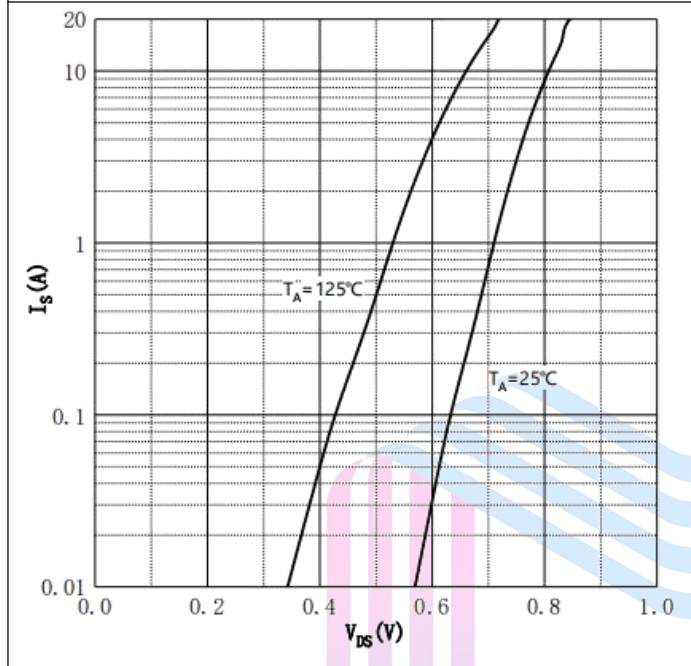
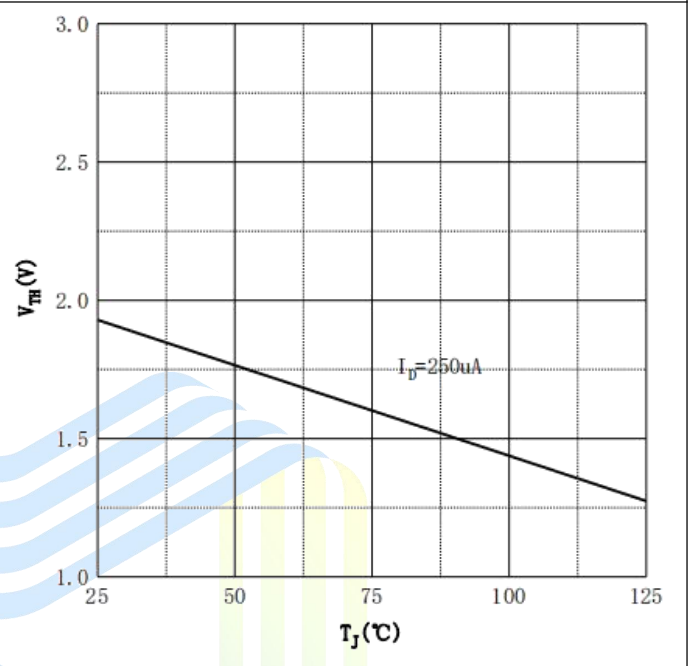
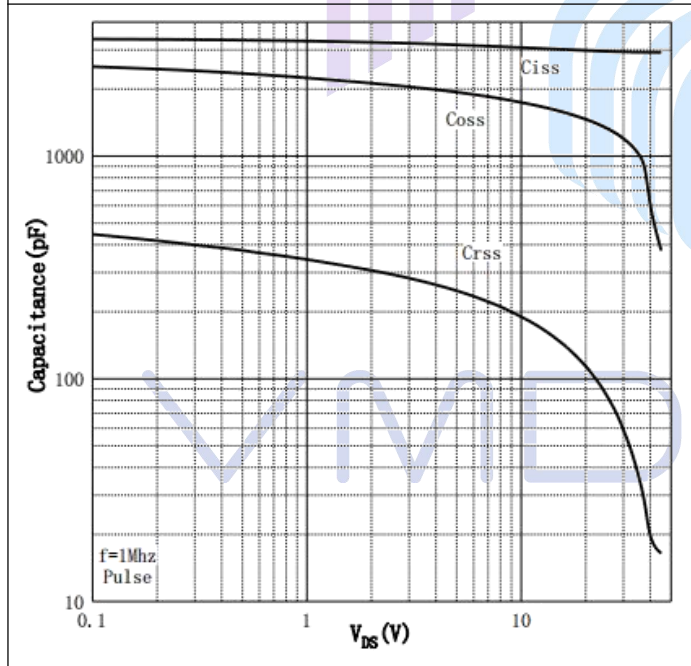
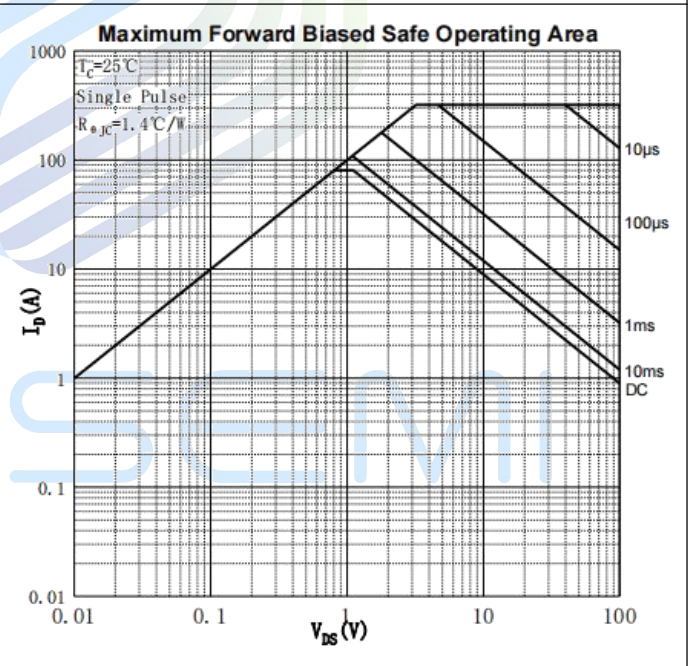
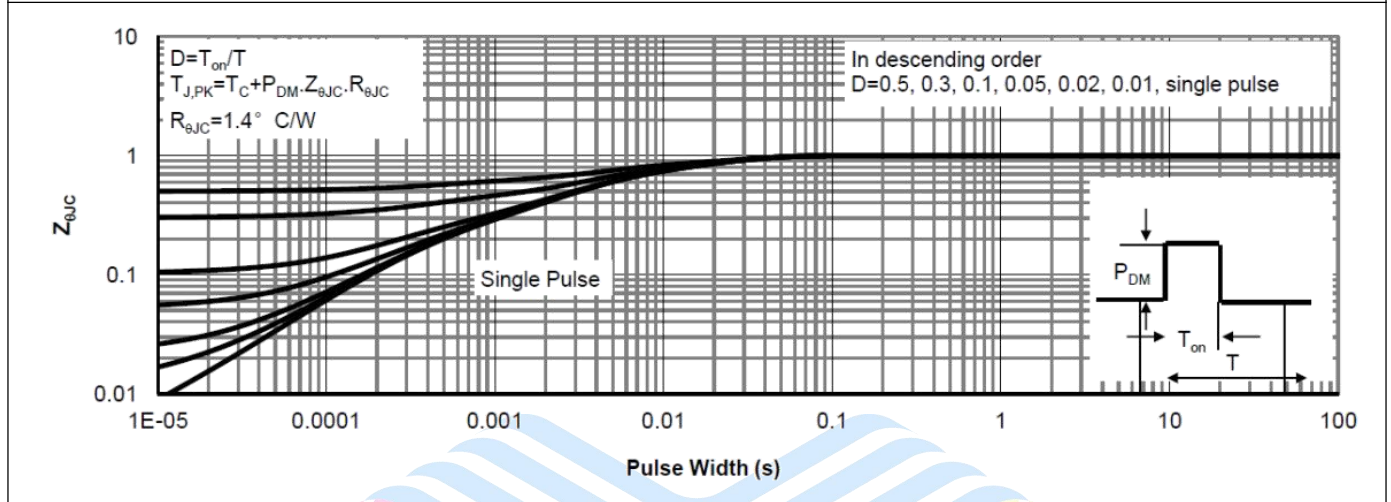
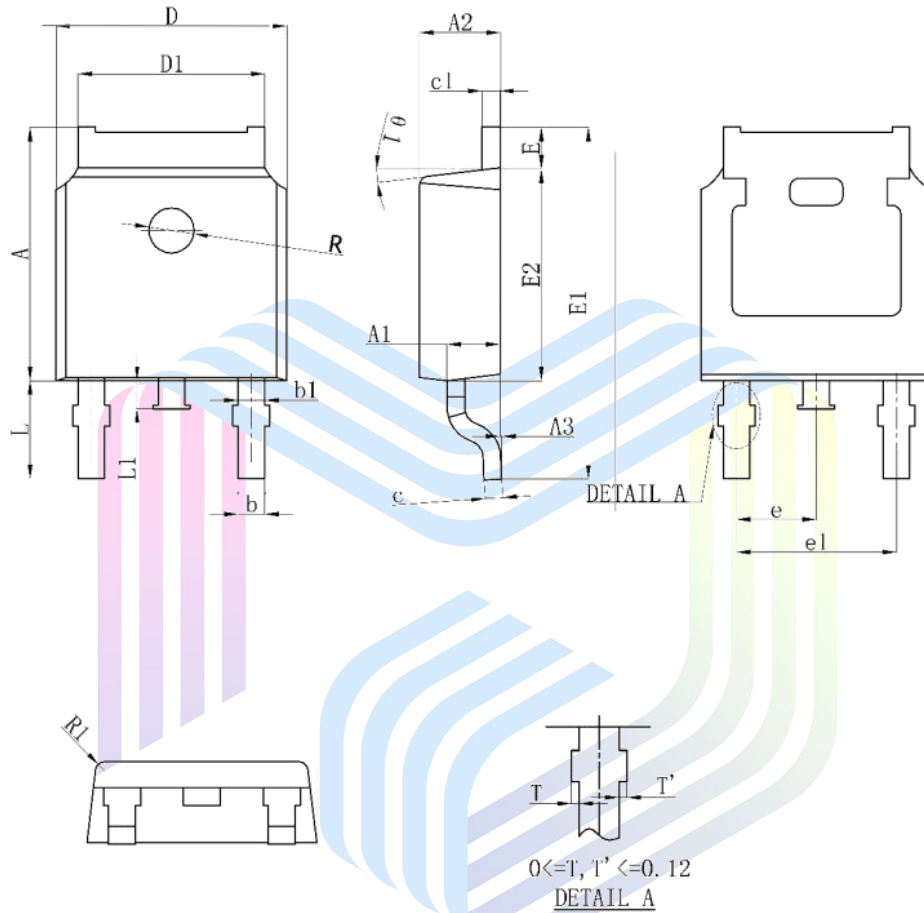
Figure 7: Body Diode Characteristics

Figure 8: Threshold Voltage

Figure 9: Typical Capacitance

Figure 10: Safe Operation Area


Figure 11: Normalized Maximum Transient Thermal Impedance



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Mechanical Dimensions:
TO-252-2L Package Information


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	7.050	7.150	0.278	0.281
A1	0.960	1.060	0.038	0.042
A2	2.200	2.400	0.087	0.094
A3	0.000	0.100	0.000	0.004
b	0.760REF		0.030REF	
b1	1.000REF		0.039REF	
c	0.508REF		0.020REF	
c1	0.508REF		0.020REF	
D	6.550	6.650	0.258	0.262
D1	5.100	5.460	0.201	0.215
E	0.950	1.050	0.037	0.041
E1	9.700	10.400	0.382	0.409
E2	6.000	6.200	0.236	0.244
e	2.286BSC		0.090BSC	
e1	4.572REF		0.180REF	
L	2.650	2.950	0.104	0.116
L1	0.700	0.900	0.028	0.035
θ1	7°REF		7°REF	
R	1.300REF		0.051REF	
R1	0.250REF		0.010REF	

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